Newsletters from MOS technology

- Precautions handling procedures for "MOS" type products
- Single cycle/single instruction Control logic (improved version of the one in the Hardware Manua)
- Order forom MOS Products
- MCS650X family Circuit modifications (ROR, Brach circuit)
- Clock generator Information
- Sales Offices and representatives for MOS Technology
- Price list



February 1976

Dear Sir:

Here is our latest newsletter updating you on our activities including new products, more detailed pricing and information on various items raised by our customers over the past few months. We are now delivering TIM chips (MCS6530-004) in volume and a special "ROM-less" MCS6530 (RAM, I/O and timer only, the MCS6530-005) in prototype systems where the mask-programmed ROM is not required.

You have recently received a brochure on our KIM-1 Microcomputer System and we have referenced that offering in both our Price List and Order Form in this mailing. We are indeed gratified by the response to this product by the marketplace.

MOS TECHNOLOGY, INC. continues to deliver the lowest cost and fastest 8 bit Microprocessor on the market. Synertek, our second source, will very shortly be delivering this product as well. We are also delivering 2 $\rm MH_Z$ microprocessors, identifiable on the price list by our "A" suffix.

Included in this newsletter are the following:

- 1. Price List indicating low volume price and delivery of the microcomputer products.
- 2. TIM Program Description providing a basic description of the features found in the pre-programmed MCS6530-004.
- MDT System Description providing a basic description of the Microcomputer Development Terminal. This sophisticated but easy to use system development tool will be available in the second quarter of 1976.
- Handling to prevent static damage some comments regarding recommended care in handling MOS TECHNOLOGY, INC. products.
- 5. Single Cycle/Single Instruction Schematic several of our customers have brought to our attention that our Static Test Control Logic Schematic on page 125 of the Hardware Manual is incorrect. We regret the delays this may have caused any of our customers who attempted to use this circuitry. The enclosed schematic will allow you to perform Single Cycle and Single Instruction executions and should be used in place of that found in the Hardware Manual.

- 6. New Order Form
- 7. Discussion of MCS650X Circuit Modifications
- 8. Discussion of Crystal and RC Time Base Generation.
- 9. Listing of MOS TECHNOLOGY, INC. Sales Representatives.
- 10. UCS Timesharing Systems Brochure for the MCS650X product line.

Our next newsletter will introduce some of our new products which will be coming out in the remainder of 1976. In the mean time, we will continue to augment our customer support activities both in the factory and in the field to keep pace with our rapidly growing customer base.

Very truly yours,

MOS TECHNOLOGY, INC.

Charles I. Peddle
Marketing Director
Microcomputers

CIP/nac Encl.

If your name or address is incorrect or if you are receiving please return this portion with the correct information.	duplicate	mailings
NAME		
COMPANY		
ADDRESS		
This is a duplicate mailing		

PRECAUTIONARY HANDLING PROCEDURES

FOR "MOS" TYPE PRODUCTS

The MCS6500 Product Line has been designed with protective circuitry to guard against static charge damage on the inputs. However, normal precautions should be taken whenever possible to prevent exposure to environments of potential static charge. The following guidelines are recommended in handling the "MOS" type products and should be used whenever possible:

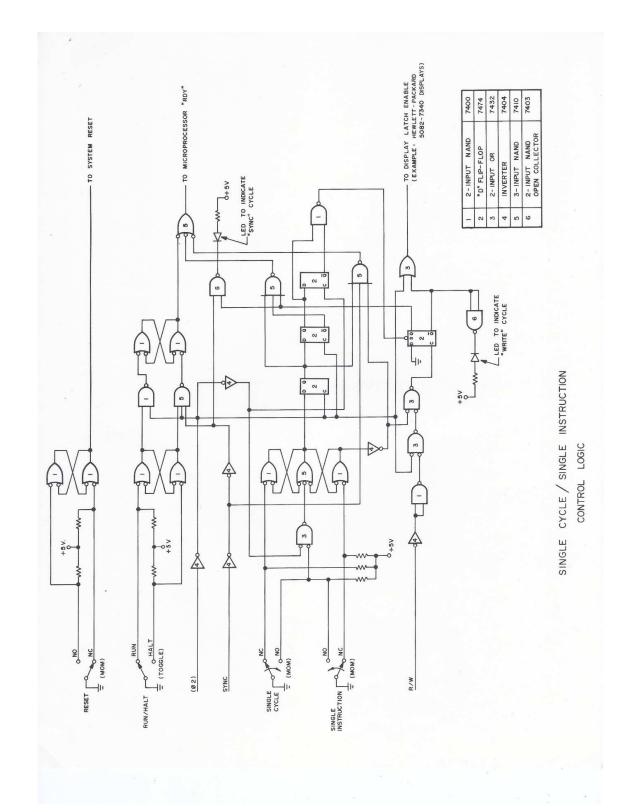
- * Keep devices in the conductive shipping carrier until used.
- * Perform work involving the 'MOS' devices on a conductive surface where possible.
- * In board assembly, place the 'MOS' devices on the boards as late in the assembly cycle as possible. For low volume applications we recommend usage of a plug-in socket for the devices.
- * Do not place the "MOS" device into position with power on. Always power up after the device is in place in the board assembly.

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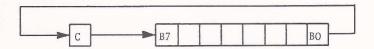


ORDER FORM

COMPONENTS	QUANTITY PRICE
MCS6501 @ \$20.00	
MCS6502A @ \$37.50	
(Includes TIM Manual)	
MCS6530-005 @ \$18.00	
KIM-1 System @ \$245.00 *	
DOCUMENTATION	
Hardware Manual @ \$5.00	
Programming Manual @ \$5.00	
Cross Assembler Manual @ \$4.00	
TIM Manual @ \$4.00	
TOTAL	
NAME Purchase	order Encl.
COMPANY Check Et	nclosed
ADDRESS	

MCS650X FAMILY CIRCUIT MODIFICATIONS

1. Since introduction of the MCS650X Family numerous customers have requested the addition of the ROR Instruction. This instruction is now being added to all MCS650X processors. The addressing modes will be Absolute (6 cycles, 3 bytes); Zero Page (5, 2); Accumulator (2, 1); Zero Page, X (6, 2); Absolute, X (7, 3). The implementation of ROR involves shifting all addressed locations one bit to the right with the carry bit shifted into Bit location 7 and Bit location 0 shifted into the carry position.



2. An additional modification is being made to the Branch, Ready circuitry. The present MCS650X processors do not execute the branch instructions correctly when the ready signal is used in the <u>Single Cycle Mode</u> if the low order effective address is FF without crossing page boundaries. For clarification the following program is executed, in both Single Cycle Mode and Single Instruction Mode.

Sar	mple Prog	ram				Sam	ple Pro	ogram E	Execu	tion	
Memory	Content	<u>s</u>	Sing	1e Cy	rcle				Sing	le Instr	uction
F5	18	CLC	ABH	ABL	DB	SYNC		ABH	ABL	DB	SYNC
F6	90	BCC	XX	F5	18	1	CLC	XX	F5	18	1
F7	07	offset	XX	F6	90	0		XX	F6	90	1
F8	A9	LDAIMM	XX	F6	90	1	BCC	XX	FF	(XXFF)	1
			XX	F7	07	0					
			XX	F8	09	0					
			XX	FF(X	X+1,FF) 1					

Note that in the Single Cycle Mode the ADH of the branch destination is incremented while in the Single Instruction Mode the branch is properly executed. The only time this occurs is when the ADL of the branch destination is FF and then only during Single Cycle with no page crossing; hence, the probability of this occurring in normal application is remote.

Availability - MCS650X microprocessors incorporating the above changes will be available in sample quantities in April with production deliveries beginning in May. Pricing for these versions of the microprocessor will be identical to the product currently being shipped.

CLOCK GENERATOR INFORMATION

Initial characterization of the MCS650X clock generator circuit has provided us with sufficient information to update the clock generator information found in our manuals and data sheets. The following discussion provides the user with information needed to obtain best performance for the time base generation scheme chosen.

Generally one would consider the following when designing systems with the $\ensuremath{\mathsf{MCS650X}}$.

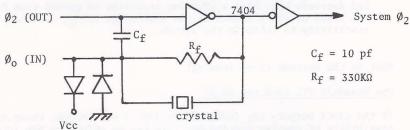
1. Which clock scheme is the best?

There is no $\underline{\text{one}}$ answer, however depending on the system there is $\underline{\text{one}}$ best way

A. TTL generated clock - drive \emptyset_0 (IN) with a TTL level clock, it doesn't require a high level clock; merely V_{OL} = .4V, V_{OH} = 2.4V. Buffer \emptyset_2 (OUT) for use as system \emptyset_2 clock. This scheme allows maximum control of all clock variables (i.e. symmetry, frequency, frequency variation from system to system).

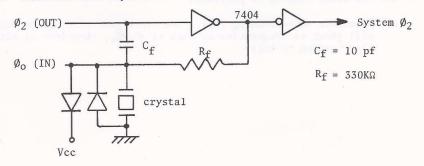
In the following discussion, reference will be made to \emptyset_{O} (IN) and \emptyset_{O} (OUT). The applicable pin numbers on the various MCS650X processors are found in the manuals or data sheets. The diodes (IN914's) are for t purposes of clamping the clock swings near ground and near V_{DD} and may not be required in all crystal applications.

B. Series Mode Crystal Controlled



This scheme allows for crystal controlled operation which is least sensitive to crystal parameters and feedback circuit variables. Because the crystal is in the feedback path and not shunting as the parallel mode crystal controlled scheme, the serial mode is most reliable from a start-up standpoint.

C. Parallel Mode Crystal Controlled



This scheme should be used when the symmetry is more desirable than the Serial Mode crystal controlled scheme symmetry. This scheme is most sensitive to feedback parameters as related to start-up. By varying the feedback resistor an appropriate combination can be found for the crystal chosen.

D. RC Controlled
$$\emptyset_2$$
 (OUT) \emptyset_0 (IN) System \emptyset_2

This scheme is recommended for those systems which do not require symmetry control, frequency variation control from system to system without manual adjustment, and systems where noise has been minimized.

Because of the ease of use of this scheme it is recommended for those systems which are in development, used as a microprocessor learning vehicle or in general systems in which noise on the clock circuit has been carefully handled (i.e. clean supply to microprocessor and clock buffers, isolate \emptyset_2 (OUT) and \emptyset_2 (IN) from stray system noise).

For frequency of operation around 1 MH $_{\rm Z}$ a value of 10K to 50K should be used with C $_{\rm f}$ = 10 pf. To decrease noise sensitivity increase C $_{\rm f}$ and decrease R $_{\rm f}$. Also a shunting capacitor to ground from \emptyset_2 (OUT) the value of which should be the same range as C $_{\rm f}$, will help to decrease sensitivity to noise in the system.

2. What is the maximum clock loading?

One standard TTL Load and 30 pf

If the clock outputs (\emptyset_1 (OUT) and \emptyset_2 (OUT)) are loaded, there is the possibility of causing overlap, but this has no effect on the internal clocks on the microprocessor. The system designer should therefore be careful if non-overlapping system clocks are necessary such that the microprocessor can function properly with overlapped clocks but system problems can develop.

· 3. How can clock ringing be prevented?

A. Eliminate noise from \emptyset_Q (IN). The clock generator on the MCS650X will react to frequencies as high as 20 MH $_Z$, therefore it will also respond to noise.

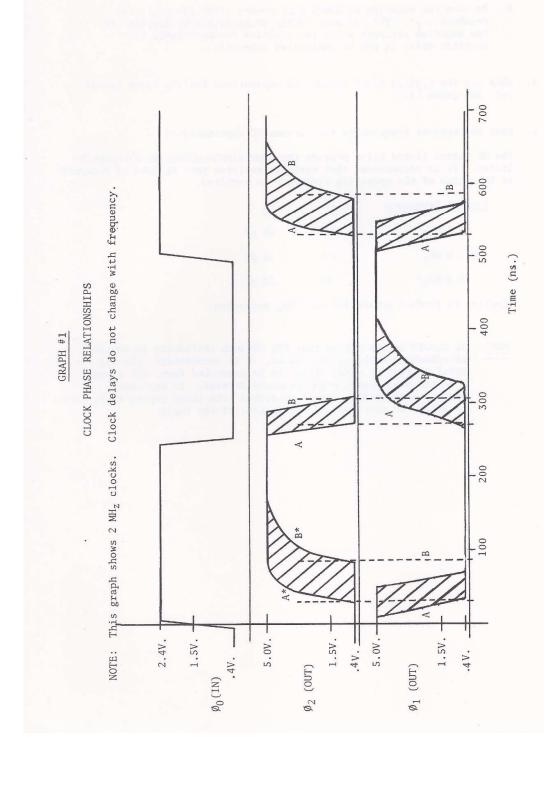
- B. Be sure the negative feedback (R_f) occurs after the positive feedback (C_f). This is most easily accomplished by tapping off the negative feedback after the positive feedback (note the inverter delay in the RC controlled schematic).
- 4. What are the typical clock widths and separations for TTL clock levels in? See graph #1.
- 5. What are typical frequencies for various RC combinations?

The RC values listed below provide the approximate operating frequencies listed. It is recommended that variable resistor pots be used if accuracy in the value of the operating frequency is required.

Typica1	Frequency	$\frac{R_{f}}{}$	$\frac{c_{\mathbf{f}}}{c_{\mathbf{f}}}$
.5	MH_Z	42K	10 pf
1.0	MH_{Z}	17K	10 pf
2.0	MH _Z *	6K	10 pf

^{*}Applies to product guaranteed at 2 $\ensuremath{\mathrm{MH}_{\mathrm{Z}}}$ operation.

NOTE: It should be understood that for maximum confidence in control of symmetry of the system clocks, it is recommended the TTL level \emptyset_0 (IN) be used. This can be generated from, for example a divide down from a high frequency crystal. In any case maximum pulse width control is formed with these inputs to \emptyset_0 (IN) in which the user has maximum control of the edges.



*Typical process related values. Edges marked "A" would correspond to part "A" Edges marked "B" would correspond to part "B"

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REGIONAL DIRECTOR

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R. G. Enterprises, Inc. 1898 So. Flatiron Ct. Boulder, CO 80301 303-447-9211

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J. A. Tudor & Associates, Inc. P. O. Box 21947 Seattle, Washington 98111 206-682-7444

NORTHERN CALIFORNIA, NORTHERN NEVADA

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JAPAN AND ITS TERRITORIES

Nihon Teksel Co., Ltd. 13-14 Sakuragaoka-Machi Shibuya-Ku, Tokyo Japan (03) 461-5121

INDIA

Mr. Dinish C. Gupta Superior Electronics El3 Dattaguru Society Deonarpada Road Bombay 400 088 India



PRICE LIST

PART NUMBER	1 - 99	100 - 999	Availability
$\begin{array}{llllllllllllllllllllllllllllllllllll$	\$ 20.00 25.00 20.00 20.00 20.00	\$ 18.00 21.00 18.00 18.00 18.00	Off the shelf
MCS6502 A* MPS6503 A MPS6504 A MPS6505 A	37.50 30.00 30.00 30.00	31.50 27.00 27.00 27.00	Off the shelf
MCS6530-004 (TIM) (Includes TIM Manua		26.00	Off the shelf
MCS6530-005 (No ROM Available)	18.00	16.00	Off the shelf
MCS6530 - Custom Program**	30.00	26.00	8 - 10 weeks after receipt of order
KIM-1 System Postage and Handlin \$4.50 - Domestic 20.00 - Internation		em	Off the shelf

^{* &}quot;A" suffix imples 2 MH_Z product

Questions concerning large volume price and delivery on all products should be directed to Mr. Julius C. Hertsch, Product Manager, MOS TECHNOLOGY, INC. $(215-666-7950 \times 220)$.

^{**} Mask tooling for custom programs is \$1,000.00 with a minimum purchase quantity of 50 units. The \$1,000.00 will be refunded if more than 1,000 units of the unique pattern is purchased within the first 12 months.